

Amendments to the Specification:

Please add the following new paragraphs after the paragraph ending on line 23 of page 6:

--FIG. 12A illustrates a side plan view of a portion of an OSA having wirebond studs formed on its bottom surface.

FIG. 12B illustrates a side plan view of an OSA having adhesive material covering the wirebond studs.

FIG. 12C illustrates a side plan view of an OSA having dispensed adhesive material covering the wirebond studs.

FIG. 12D illustrates a side plan view of a CSA placed on bottom of an OSA such that the electrical contact surfaces of the CSA are aligned with the wirebond studs.

FIG. 12E illustrates a side plan view of a CSA joined to an OSA where underfill material fills the gaps between the wirebond studs that connect the two subassemblies.--

Please replace the paragraph beginning at page 8, line 20, with the following rewritten paragraph:

-- It is preferable to form the wirebond studs on the CSA's rather than the OSA's because the CSA's are typically aligned in a matrix of columns and rows during manufacturing processes. Therefore, it is more efficient to form the wirebond studs using automated processes while the CSA's are in the matrix during these manufacturing processes. However, in alternative embodiments of the invention, it is possible to form the wirebond studs on the OSA rather than the CSA (e.g., FIG. 12A-12E).--

Please replace the paragraph beginning at page 9, line 4, with the following rewritten paragraph:

-- The adhesive material can be epoxy, conductive solder, or an appropriate glue material. In the case that the wirebond studs 204 were formed on an OSA rather than the CSA, then it follows that the adhesive material would be placed on the OSA to cover the wirebond studs (e.g., FIGS. 12B & 12C).--